ON Semiconductor

Initial Product/Process Change Notification

Document # : IPCN21457X
Issue Date: 7 September 2016

Title of Change:	The PTIC Fab process is being transferred from the ON Semiconductor facility in Burlington, Canada to the ON Semiconductor facility in Niigata, Japan
Proposed first ship date:	3 April 2017 or earlier after customer approval
Contact information:	Contact your local ON Semiconductor Sales Office or <Scott.Haddow@onsemi.com>
Samples:	Samples should be available after completion of qualification. Contact your local ON Semiconductor Sales Office.
Type of notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. IPCNs are issued at least 30 days prior to the issuance of the Final Change Notice (FPCN). An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>.
Change Part Identification:	Affected product will be identified with date code.
Change category:	☒ Wafer Fab Change ☐ Assembly Change ☐ Test Change ☐ Other _____

Change Sub-Category(s):

☒ Manufacturing Site Change/Addition
☐ Manufacturing Process Change
☐ Material Change
☐ Product specific change
☐ Datasheet/Product Doc change
☐ Shipping/Packaging/Marking
☐ Other: _____

Sites Affected:

☐ All site(s) ☐ not applicable
☒ ON Semiconductor site(s) :
ON Burlington, Canada
On Niigata, Canada
☐ External Foundry/Subcon site(s)

Description and Purpose:

PTIC Fab process is going to be moved from the ON Semiconductor facility in Burlington, Canada to the ON Semiconductor facility in Niigata, Japan. The purpose of this change is to increase the capacity and reduce the cost.

Qualification Plan:

Test	Specification	Condition	Interval	Target results
HTOL	JESD22-A108	Ta= 125°C, 83 % max rated Vcc =24V	5 hrs	Pending
ELFR	JESD22-A108	Ta= 125°C, 20V	1.5 hrs	Pending
HTSL	JESD22-A103	Ta= 150°C	500 hrs	Pending
TC	JESD22-A104	Ta= -55°C to +125°C	500 cyc	Pending
THB	JESD22-A101	85°C / 85%RH; Bias at 12V	500 hrs	Pending
PC	J-STD-020 JESD22-A113	MSL 1 @ 85 °C, 85 %H	168 hrs	Pending
Constr A	12MRM94918A	Construction analysis, SEM, FIB, TEM	NA	Pending

Estimated date for qualification completion: 16 December 2016

List of affected Standard Parts:

Part Number	Qualification Vehicle
TCP-4112UB-DT	TCP-4127UA-DT TCP-4182UB-DT TCP-4147UB-DT
TCP-4118UB-DT	
TCP-4127UB-DT	
TCP-4127UA-DT	
TCP-4133UB-DT	
TCP-4139UB-DT	
TCP-4147UB-DT	
TCP-4156UB-DT	
TCP-4168UB-DT	
TCP-4182UB-DT	